

## P-M5.1

Wire Bond Mold Package  
For contact based application (Controller)

## Short Product Overview

May 2010

Chip Card & Security

<b>P-M5.1 Short Product Overview</b>		Ref.: Chip_Card_Product_Overview_11/09
<b>Revision History: Current Version 05.10</b>		
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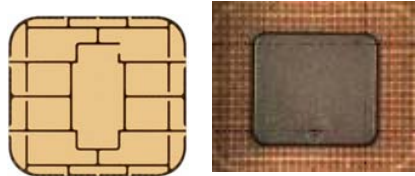
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<b>Product name</b>	<b>P-M5.1</b>
<b>Picture</b>	
<b>Product description</b>	Contact based module 8 contacts Epoxy Tape Wire Bond Mold
<b>Typical Applications</b>	Payment, Government Identification
<b>Pitch</b>	14.25 mm
<b>Dimensions</b>	13 x 11.8 mm
<b>Thickness</b>	max. 600µm
<b>Contact Surface</b>	CIN+
<b>Delivery form</b>	Tape on Reel Reel diameter 330mm
<b>ISO - reference</b>	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
<b>Derivatives</b>	

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